

JSO22 Series Material Declaration

Total Weight: 10,5 mg
Size: 2.5 x 2.0 x 0.75 mm



RoHS (2011/65/EC) compliant



Part	Weight of parts (mg)	Content substance	CAS No	Content (mg)	Content (wt%)	
Leadframe	3.449	C194 Alloy	Copper	7440-50-8	3.364	32.09
			Iron	7439-89-6	0.081	0.77
			Zinc	7440-66-6	0.004	0.04
Plating	0.048	NiPdAu	Nickel	7440-02-0	0.046	0.44
			Palladium	7440-05-3	0.001	0.01
			Gold	7440-57-5	0.001	0.01
Die 1	0.5	CEMOS Die	Si	7440-21-3	0.500	4.77
Die 2	0.04	MEMS Die	Si	7440-21-3	0.040	0.38
Die attach material 1	0.256	Non-Conductive epoxy	Epoxy Resin	Proprietary	0.179	1.72
			Glycol Ether	25068-38-6	0.038	0.36
			Fused Silica	60676-86-0	0.020	0.19
			Additive	Proprietary	0.018	0.17
Die attach material 2	0.022	Conductive epoxy	Silver	7440-22-4	0.017	0.16
			Acrylate	Proprietary	0.004	0.04
			Resin	Proprietary	0.001	0.01
			Additive	Proprietary	<0.001	Trace
Wire	0.1	Gold	Au	7440-57-5	0.100	0.95
Encapsulation	6.069	Epoxy Resin	Fused silica	60676-86-0	5.493	52.39
			Epoxy resin	Proprietary	0.285	2.72
			Phenol resin	Proprietary	0.285	2.72
			Carbon black	1333-86-4	0.006	0.06